



Material Content Data Sheet



Sales Product Name		SAB-C167CR-LM HA+		Issued		25. September 2017		
MA#		MA000106568						
Package		PG-MQFP-144-8		Weight*		4197.93 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	25.986	0.62	0.62	6190	6190
leadframe	non noble metal	magnesium	7439-95-4	0.976	0.02		232	
	inorganic material	silicon	7440-21-3	4.227	0.10		1007	
	non noble metal	nickel	7440-02-0	19.510	0.46		4648	
	non noble metal	copper	7440-50-8	625.625	14.90	15.48	149032	154919
wire	noble metal	gold	7440-57-5	7.259	0.17	0.17	1729	1729
encapsulation	organic material	carbon black	1333-86-4	10.438	0.25		2487	
	plastics	epoxy resin	-	441.893	10.53		105264	
	inorganic material	silicondioxide	60676-86-0	3027.140	72.13	82.91	721103	828854
leadfinish	non noble metal	tin	7440-31-5	19.066	0.45	0.45	4542	4542
plating	noble metal	silver	7440-22-4	10.582	0.25	0.25	2521	2521
glue	plastics	acrylic resin	-	1.045	0.02		249	
	noble metal	silver	7440-22-4	4.180	0.10	0.12	996	1245
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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